

Appendix to Amendment of August 7, 2002

IN THE CLAIMS:

Please amend claims 1-5, 8-12, and 14, as follows:

1. (Amended) A circuit board for transmitting signals, comprising:

a dielectric layer;

a signal line configured as a pattern on the dielectric layer to transmit the signals;

a pad formed on the dielectric layer, the pattern connected to and extending away from the pad;

a ground/power supply layer formed under the dielectric layer and having a rectangular hole below the pad,

wherein a longitudinal length of the rectangular hole [extending] extends in a direction substantially parallel with a direction of the pattern extending away from the pad and the longitudinal length of the rectangular hole may be adjustable along a longitudinal length of the pad.

2. (Amended) The circuit board of claim 1, wherein:

the rectangular hole is [rectangular and] formed outside an imaginary line extending the pattern.

3. (Amended) The circuit board of claim 1, wherein:

the rectangular hole [is rectangular and] has a width wider than that of the pattern and narrower than that of the pad.

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4. (Amended) The circuit board of claim 1, wherein:

the rectangular hole comprises a pair of rectangular holes formed below the pad and outside imaginary lines extending the pattern and a third rectangular hole formed between the imaginary lines.

5. (Amended) The circuit board of claim 1, wherein:

the rectangular hole comprises a pair of rectangular holes formed below the pad outside imaginary lines extending the pattern.

8. (Amended) The circuit board of claim 1, wherein:

the rectangular hole is [rectangular and] formed between imaginary lines extending the pattern.

9. (Amended) A method for producing a circuit board for transmitting signals, comprising:

forming a dielectric layer;

forming a signal line configured as a pattern on the dielectric layer to transmit the signals;

forming a pad on the dielectric layer and connected to the pattern; and

forming a ground/power supply layer under the dielectric layer including a rectangular hole below the pad, wherein a longitudinal length of the rectangular hole [extending] extends in a direction substantially parallel with a direction of the pattern

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extending away from the pad and the longitudinal length of the rectangular hole may be adjustable along a longitudinal length of the pad.

10. (Amended) The method of claim 9, wherein forming the ground/power supply layer includes:

forming the rectangular hole [as a rectangular hole] outside an imaginary line extending the pattern.

11. (Amended) The method of claim 9, wherein forming the ground/power supply layer includes:

forming the rectangular hole [as a rectangular hole having] to have a width wider than that of the pattern and narrower than that of the pad.

12. (Amended) The method of claim 9, wherein forming the ground/power supply layer includes:

forming the rectangular hole as a pair of rectangular holes below the pad outside imaginary lines extending the pattern and a third rectangular hole formed between the imaginary lines.

14. (Amended) The method of claim 9, wherein forming the ground/power supply layer includes:

forming the rectangular hole [as a rectangular hole] between imaginary lines extending the pattern.

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